

WLCSP68, wafer level chip-scale package, 68 terminals; 0.35 mm pitch, 3.78 mm x 3.06 mm x 0.49 mm body (backside coating included)

25 May 2018

Package information

1. Package summary

Terminal position code B (bottom)

Package type descriptive code WLCSP68

Package style descriptive code WLCSP (wafer level chip-size package)

Mounting method type S (surface mount)

Issue date 16-5-2018

Manufacturer package code 98ASA01214D

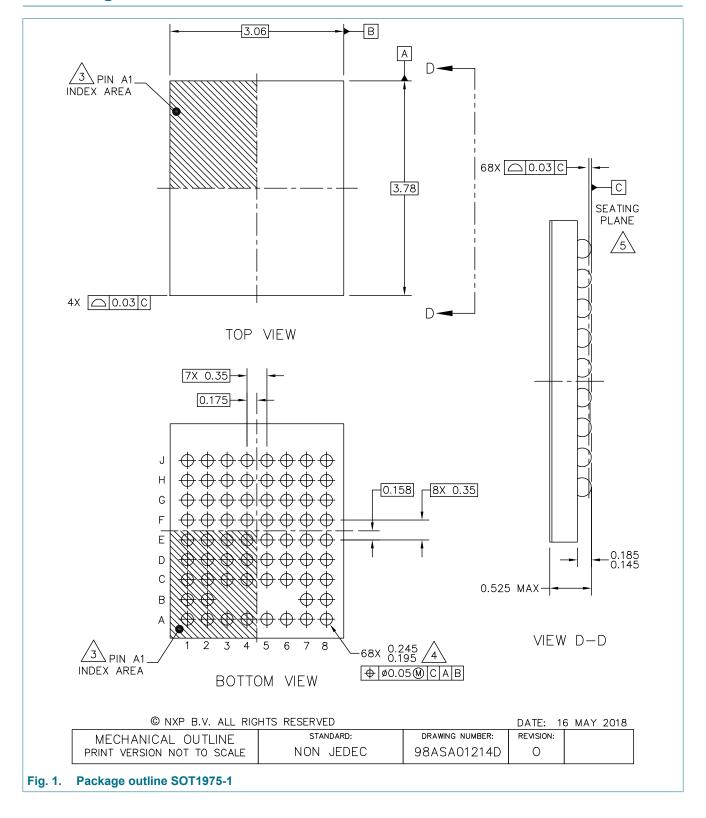
Table 1. Package summary

Table 11 Table 20 Califfred							
Parameter		Min	Nom	Max	Unit		
package length		-	3.78	-	mm		
package width		-	3.06	-	mm		
seated height		-	0.49	-	mm		
nominal pitch		-	0.35	-	mm		
actual quantity of termination		-	68	-	A/A		



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2. Package outline



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NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.

DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

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DATE: 16 MAY 2018 STANDARD: DRAWING NUMBER: REVISION: MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE NON JEDEC 0 98ASA01214D

Package outline note WLCSP68 (SOT1975-1) Fig. 2.

WLCSP68, wafer level chip-scale package, 68 terminals; 0.35 mm pitch, 3.78 mm x 3.06 mm x 0.49 mm body (backside coating included)

3. Soldering

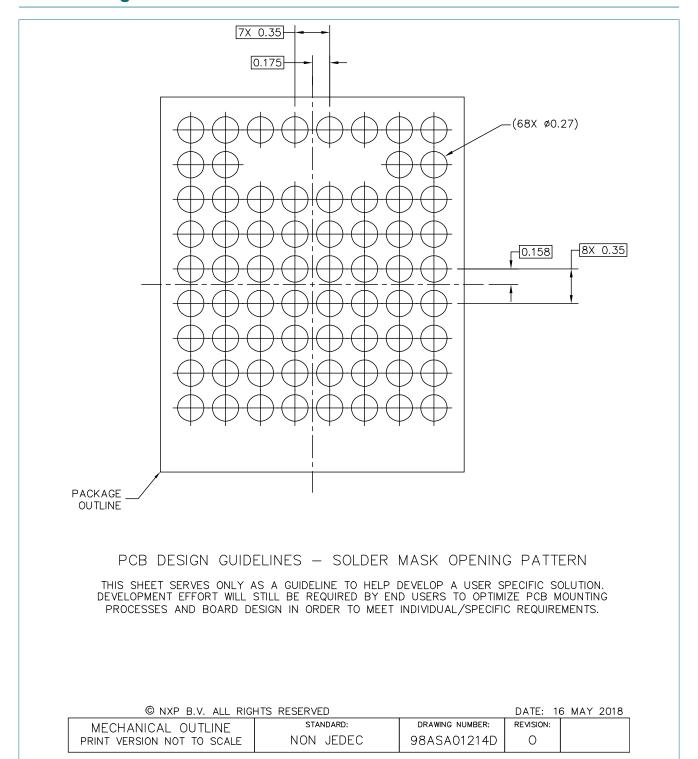


Fig. 3. Reflow soldering footprint for SOT1975-1

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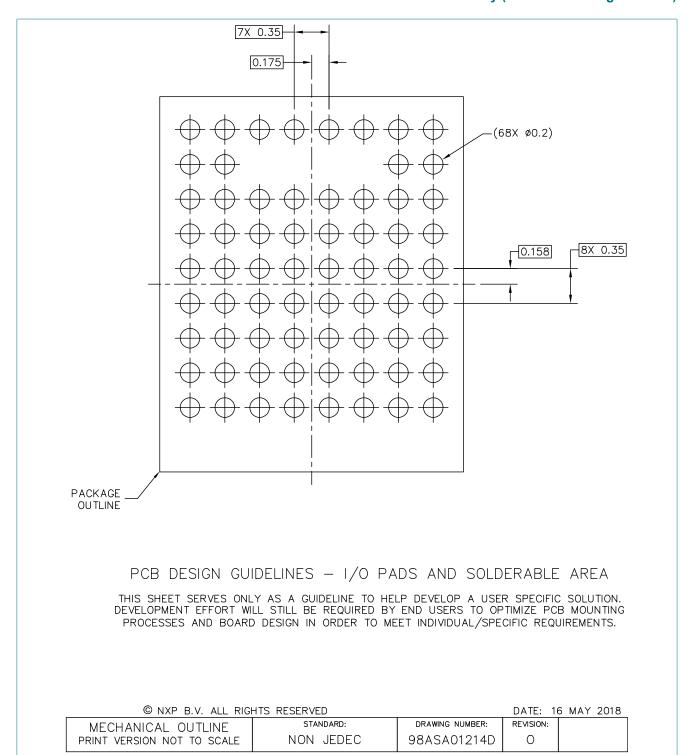
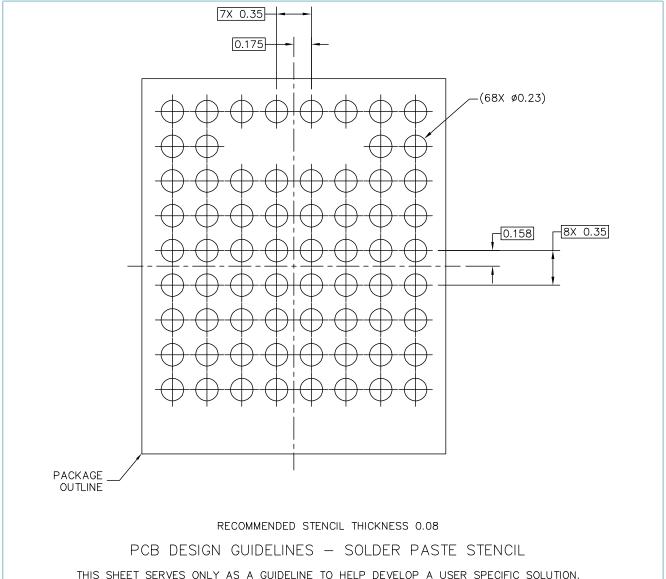


Fig. 4. Reflow soldering footprint part2 for WLCSP68 (SOT1975-1)

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Fig. 5. Reflow soldering footprint part3 for WLCSP68 (SOT1975-1)

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5. Contents

1.	Package summary	1
2.	Package outline	2
3.	Soldering	4
4.	Legal information	7
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